12th IEEE CPMT Symposium Japan (ICSJ2023)

The Leading International Components, Packaging and Manufacturing Technology Symposium

November 15-17, 2023
Ritsumeikan University's Suzaku Campus, Kyoto, Japan

Advanced Program

Last update: September 6, 2023

November 15, 2023 (Wednesday)

Time	4F/5F Main Hall I On-site presentation		1F Room I On-site presentation		1F Room II On-site presentation	
9:00			*Registration*			
10:20	*Opening Remark (General Chair) (Hall I)*					
10:35	*Award Ceremony (Hall I)*					
10:50-12:30	**Hall I** **Chairperson Hideyuki Nasu (Furukawa Electric Co., Ltd), Takaaki Ishigure (Keio University)** **Plenary Speech I & II**					
10:50	**Plenary Speech I : Silicon Photonics for Chiplet (TBD)** ***Mark Wade (Ayar Lab)***					P-02
11:40	**Plenary Speech II : Co-Package Optics is the big next thing: What happened?** ***Daniel M. Kuchta (IBM T. J. Watson Research Center)***					P-03
12:30-12:50			*Platinum Sponsors' Seminar (with a light meal) @Meetiing Room 1* *Title : TBD (TBD)*			
12:55-13:15			*Platinum Sponsors' Seminar (with a light meal) @Meetiing Room 1* *Title : TBD (TBD)*			
13:30-15:25	**Session 1: Co-packaged Optics** **Chairperson** **Takahiro Matsubara (KYOCERA Corporation)** **Hidetoshi Numata (IBM Research)**		**Session 2: Advanced PKG I** **Chairperson** **Shoji Uegaki (Crane Research)** **Chinami Marushima (IBM Japan, Ltd.)**		**Session 3: Process and Material Technologies I** **Chairperson** **Shinya Takyu (LINTEC Corporation)** **Kei Murayama(SHINKO ELECTRIC INDUSTRIES CO., LTD.)**	
13:30	Pigtailed-OSFP External Laser Source for Co-Packaged Optics *Kohei Umeta, Taketsugu Sawamura, Kyoko Nagai, Kazuhiko Kashima, Hideyuki Nasu* *Furukawa Electric Co., Ltd*	24	**(Invited)** (TBD) *Takeyasu Saito* *Osaka Metropolitan University*	I-07	**(Invited)** Atomic imaging of Al_2O_3/diamond interface by photoelectron *Mami N. Fujii* *Kindai University*	I-05
13:55	Bandwidth Expansion of a Testing Station using a 0.3-mm-Pitch LGA Interface for a 25-Gbaud x 16-channel CPO Transceiver *Kazuya Nagashima, Yuta Ishige, Wataru Yoshida, Hideyuki Nasu* *Furukawa Electric Co., Ltd*	31	Polishing of CVD Diamond for Direct Bonding using Ar and SF6-Gas Cluster Ion Beams *Junsha Wang[1], Tadatomo Suga[1], Hideaki Yamada[2], Yoshiaki Mokuno[2]* *1) Meisei University 2) AIST*	58	Influence of EMC Tg on Leakage Current in HTRB Test and Delamination in MSL Test for Power Package *ZHIWEN LI, OU DONG, JUANJUAN HUANG, JUNRUI PENG* *Nexperia*	19
14:20	Jitter Margin Analysis of 56-Gb/s PAM4 × 8-Channel VCSEL-Based Optical Transceiver for Co-Packaged Optics *Wataru Yoshida, Yuta Ishige, Kazuya Nagashima, Hideyuki Nasu* *Furukawa Electric Co., Ltd*	29	Pillar-Concave Copper-Copper Bonding for Face-to-Face Carbon Nanotube Synthesis *Hua XU, Jeffery C.C. LO, S.W. Ricky LEE* *The Hong Kong University*	63	Reliability Performance Study of Molding Compounds on High Voltage Molded Leaded Package *April Joy Garete, Zhiwen Li, Yee Wai Fung, Wai Man Wong* *Nexperia*	1
14:45	Temperature Distribution Measurement System for a Water-Cooled CPO Daughter Board *Yuta Ishige, Kazuya Nagashima, Wataru Yoshida, Takeshi Hirasawa, Hideyuki Nasu* *Furukawa Electric Co., Ltd*	62	Nb-Nb direct bonded pads for superconducting devices and their failure mode *Atsushi Kudo[1], Masahisa Fujino[2], Yuuki Araga[2], Hiroshi Nakagawa[1], Katsuya Kikuchi[2], Tohru Taino[1]* *1) Saitama University 2) AIST*	44		
15:10	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*		*Interview with the Authors (Discussion after the session)*		*Interview with the Authors (Discussion after the session)*	
15:25			*Coffee break + Sponsor's Exhibition*			
15:40-17:35	**Session 4: Photonics Packaging** **Chairperson** **Takaaki Ishigure (Keio University)** **Hideyuki Nawata (Nissan Chemical Corporation)**		**Session 5: Bioelectronics** **Chairperson** **Beomjoon Kim (The University of Tokyo)** **Takafumi Fukushima (Tohoku University)**		**Session 6: Technical Session** **Chairperson** **Shigenori Aoki (LINTEC Corporation)** **Takashi Hisada (IBM Research-Tokyo)**	
15:40	**(Invited)** 2.5D Photonic Integration for GPU Interconnects *Benjamin Lee* *NVDIA Corporation*	I-01	FOWLP-based Flexible Hybrid Electronics (FHE) I: Photobiomodulation Device Fabrication on Hydrogel Substrate Using RDL-first Approach *Tadaaki Hoshi, Daichi Nishiguchi, Hisashi Kino, Tetsu Tanaka, Takafumi Fukushima* *Tohoku University*	54	TC-6 No.1 High Density Substrates & Boards *TC-6 (TBD)*	
16:05	Development of Adapter-less Compact Multifiber Optical Connector *Alexander William Setiawan Putra, Kentaro Matsuda, Motohito Takezaki* *Hakusan Inc.*	20	FOWLP-based Flexible Hybrid Electronics (FHE) II: Heterogeneous Integration Technology of Micro-LEDs on 3D-IC for Smart Skin Display *Jiayi Shen, Chang Liu, Hisashi Kino, Tetsu Tanaka, Takafumi Fukushima* *Tohoku University*	60	TC-6 No.2 High Density Substrates & Boards *TC-6 (TBD)*	
16:30	High Density Optical Transceiver Packaging using Glass Substrates and Through Glass Vias *Kevin Burt, Joe Ahadian, Chris Bohn, John Coronati, Marc Epitaux, Adam Owens, Nathan Roberson, Sandra Skendzic* *Samtec Inc.*	65	Enhancement for extraction of interstitial fluid through the porous microneedles array patch made of polycaprolactone (PCL) *Yosuke Koma, Yuko Tsuruma, Shigenori Aoki, Shinya Takyu, Jongho Park, Beomjoon Kim, Rie Kinoshita* *1) LINTEC Corporation* *2) The University of Tokyo*	34	TC Materials and Processes (TBD) *(TBD)*	
16:55	Unique optical connect structure with polymer waveguide fabricated by the Mosquito method *Yuji Furuta, Anzu Ito, Ryoto Ichinose, Hisashi Kaneda, Tomoharu Fujii, Takaaki Ishigure* *1) SHINKO ELECTRIC INDUSTRIES C., LTD. 2) Keio University*	36	Development of a highly porous polycaprolactone (PCL) Microneedles Array Patch to improve the absorption of interstitial fluid (ISF) *Yosuke Koma, Yuko Tsuruma, Shigenori Aoki, Shinya Takyu, Jongho Park, Beomjoon Kim, Rie Kinoshita* *1) LINTEC Corporation* *2) The University of Tokyo*	33	TC Thermal and Mechanical (TBD) *(TBD)*	
17:20	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*		*Interview with the Authors (Discussion after the session)*		*Interview with the Authors (Discussion after the session)*	
17:35-18:15	**Hall I** **Chairperson Shinya Takyu (LINTEC Corporation) & Eiji Higurashi (Tohoku University)** **IEEE EPS Special Speech I**					
17:35	**IEEE EPS Special Speech I： EPS Welcome** ***Kitty Pearsall (Boss Precision, Inc.)***					S-02
19:15			***Welcome Reception***			
21:15			*Close*			

November 16, 2023 (Thursday)

Time	4F/5F Main Hall I On-site presentation		1F Room I On-site presentation		1F Room II On-site presentation	
9:00	*Registration*					
9:20- 10:10	**Hall I** **Chairperson Shoji Uegaki (Crane Research) & Kazuyuki Nakagawa (Renesas Electronics Corporation)** **Plenary Speech III**					
9:20	**Plenary Speech III: Pivotal Advanced Package Co-Design for Heterogeneous Integration** ***C.P. Hung (ASE Group)***					P-04
10:10- 11:00	**Hall I** **Chairperson Yoichiro Kurita (Tokyo Institute of Technology) & TBD** **Plenary Speech IV**					
10:10	**Plenary Speech IV: （TBD)** ***Seungwook Yoon (Samsung Electronics Corp.)***					P-01
11:00	*Coffee break + Sponsor's Exhibition*					
11:10- 12:40	**Session 7: Advanced PKG II** **Chairperson** **Kiyokazu Yasuda (Osaka University)** **Kenji Takahashi (AIST)**		**Session 8: Automotive I** **Chairperson** **Hajime Kimura (Nissan Motor Co., Ltd.)** **Yutaka Uematsu (Hitachi Ltd.)**		**Session 9: VCSEL-Based Optical Interconnects** **Chairperson** **Hideyuki Nasu (Furukawa Electric Co., Ltd** **Junichi Inoue (Kyoto Institute of Technology)**	
11:10	**(Invited)** Metal-polymer direct joining using small textures on metal surface *Yusuke Kajihara* *Tokyo University*	I-06	Packaging of SiC Power Module with a Low-Permittivity Material to Reduce Capacitive Coupling *Sihoon Choi[1], Jiyoon Choi[1], Jong-Won Shin[2], Jun Imoka[1], Masayoshi Yamamoto[1]* *1) Nagoya University 2) Chung-Ang University*	30	**(Invited)** TBD *Michael Tan* *Lumentum*	I-09
11:35	Multi Die Stacked Structure fabricated by WoW Bonding *Haruo Shimamoto[1], Yuuki Araga[1], Masahisa Fujino[1], Naoya Watanabe[1], Kenji Takahashi[1], Tsuyoshi Kawagoe[2], Ichirou Honma[2], Katsuya Kikuchi[1]* *1) AIST* *2) UltraMemory Inc.*	52	A Review of the Packaging Scheme of a Traction Inverter: Layout, Capacitor, Current Sensing and Power Module *Thiyu Warnakulasooriya, Sihoon Choi, Arihiro Kamiya, Jun Imaoka, Masayoshi Yamamoto* *Nagoya University*	39	Crosstalk Reduction in Ultra-High-Density High-Speed Optical Receiver *Takatoshi Yagisawa, Tomonori Azuma, Makoto Miyoshi, Jumpei Miike, Yoshiyuki Harada, Satoshi Ide* *Fujitsu Optical Components Limited*	48
12:00	Packaging of a 25-tiles device on large dimension AlN ceramic substrate keeping low dead areas and tight planarity *Sarah Renault* *CEA-Leti*	59	Abnormal Position Identification Technique for Communication Channel using Adaptive DFE *Soshi Shimomura, Yutaka Uematsu* *Hitachi Ltd.*	7	Polymer Optical Waveguide Coupler with Vertically Bent Cores *Nagi Itaru, Takaaki Ishigure* *Keio University*	9
12:25	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*		*Interview with the Authors (Discussion after the session)*		*Interview with the Authors (Discussion after the session)*	
12:40- 14:10	*Lunch*					
14:10- 15:40	**Session 10: Automotive II** **Chairperson** **Yutaka Uematsu (Hitachi Ltd.)** **Hajime Kimura (Nissan Motor Co., Ltd.)**		**Session 11: Millimeter Wave applications** **Chairperson** **Kazuyuki Nakagawa (Renesas Electronics Corporation)** **Yoichiro Kurita (Tokyo Institute of Technology)**		**Session 12: Advanced PKG III** **Chairperson** **Kenji Takahashi (AIST)** **Taiji Sakai (FICT LIMITED)**	
14:10	**(Invited)** The Cutting-edge Simulation and Validation Technology using Model-based Development *Karsten Krügel* *dSPACE GmbH*	I-02	Design and Optimization of Test Socket for Millimeter-Wave Steerable Beam Measurement Technology *Yu-Chang Hsieh, Hong-Sheng Huang, Wen-Chun Hsiao, Sheng-Chi Hsieh, Chen-Chao Wang* *ASE Inc.*	16	Understanding Design Rules of Wafer Level Chip Scale Packaging Addressing Thermo-Mechanical Challenges *Yiyi Ma, Jing-En Luan* *STMicroelectronics*	2
14:35	High Density Automotive Module with Fan-Out Package *Wataru Shiroi, Shuuichi Kariyazaki, Yuji Kayashima, Takafumi Betsui, Shiro Machida, Kazuyuki Nakagawa, Toshihiko Akiba* *Renesas Electronics Corporation*	40	Ceramic-packaged Multichip Front-end Module for 5G Millimeter Wave Communication applications *Bo Zhou, Zheng Pan, Yong Cheng* *Nanjing University of Posts and Telecommunications*	12	A DfT Technique for Electrical Interconnect Testing of Circuit Boards with 3D Stacked SRAM ICs *Yuki Ikiri[1], Hiroyuki Yotsuyanagi[1], Fara ASHIKIN Binti Ali[2], Shyue-Kung Lu[3], Masaki Hashizume[4]* *1) Tokushima University* *2) Universiti Teknikal Malaysia* *3) National Taiwan Univ.* *4) The Open Univ. of Japan*	15
15:00	Board-Level Drop Reliability Analysis for Fine-Pitch BGA Packages in Automotive Applications *Wei-Hong Lai* *ASE Inc.*	28				
15:25	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*		*Interview with the Authors (Discussion after the session)*		*Interview with the Authors (Discussion after the session)*	
15:40	*Coffee break + Sponsor's Exhibition*					
15:50- 16:30	**Hall I** **Masayoshi Yamamoto (Nagoya University) & Yutaka Uematsu (Hitachi, Ltd.)** **Special Speech I**					
15:50	**Special Speech I: Special Speech I: Dynamic Wireless Power Transfer Technologies for Future Electric Vehicles** ***Takehiro Imura (Tokyo University of Science)***					S-05
16:30- 17:10	**Hall I** **Chairperson Shinya Takyu (LINTEC Corporation) & Eiji Higurashi (Tohoku University)** **IEEE EPS Special Speech II**					
16:30	**IEEE EPS Special Speech II：TBD** ***Sam Karikalan (Broadcom Inc.)***					S-01
17:10	*Coffee break + Sponsor's Exhibition*					
17:20- 18:20	**Early Career Researcher's (ECR) Session** On-site poster presentation					
	A D-Band Waveguide-feed Patch Array on GaAs IPD Process *Ta-Yeh Lin, Shuw-Guann Lin, Yin-Cheng Chang, Chaoping Hsieh, Tsenchieh Chiu, Da-Chiang Chang* *National Central University*	4	Fabrication of Polymer Optical Waveguide Based Splitter by the Mosquito Method and Investigation of Its Signal Splitting Ratio *Kosei Azuma, Takaaki Ishigure* *Keio University*	11	Structural Investigation of Rare-Earth Metal Polymer Composite Doped Optical Amplifiers for Higher Gain *Kohei Ono, Takaaki Ishigure* *Keio University*	14
	Polymer Spot Size Expander on Laser Diode Chip for Fiber Coupling *Atsuki Sawada[1], Yoshiki Kamiura[2], Chiemi Fujikawa[1], Osamu Mikami[3]* *1) Tokai University 2) Kyushu University* *3) Universiti Teknologi Malaysia*	26	Study on Power Transmission System for a Dynamic Charging System Shared Between Light-Duty and Heavy-Duty Vehicles *Kouki Onimaru, Kraisorn Throngnumchai* *Kanagawa Institute of Technology Graduate School*	32	Reserch on strain sensor using bending loss of optical fiber *Takaya Waki, Masaki Fujii, Ryo Nagase* *Chiba Institute of Technology*	43
	Template stripping of Au from polyimide film for smoothing of bonding surface *Shogo Koseki[1], Mika Ogino[1], Kai Takeuchi[1], Le Hac Huong Thu[2], Takashi Matsumae[2], Hideki Takagi[2], Yuichi Kurashima[2], Tomoaki Tokuhisa[3], Toshikazu Shimizu[3], Eiji Higurashi[1]* *1) Tohoku University 2) AIST* *3) Kanto Chemical Co., Inc.*	47	Suppression of surface roughening of Ag films by capping layer for Ag/Ag surface activated bonding *Yuanhao Cai[1] Kai Takeuchi[1] Miyuki Uomoto[2] Takehito Shimatsu[2], Eiji Higurashi[1]* *1) Tohoku University* *2) FRIS, Tohoku University*	49		
18:20	*Close*					

November 17, 2023 (Friday)

Time	4F/5F Main Hall I	No.	1F Room I	No.	1F Room II	No.
	On-site presentation		**On-site presentation**		**On-site presentation**	
9:00	*Registration*					
9:20	*ECR Award Ceremony*					
9:30-10:10	**Hall I** **Chairperson Kenji Takahashi (AIST) ＆ TBD** **Special Speech II**					
9:30	**Special Speech II: （TBD）** ***Yoshihiro Hayashi (AIST/Keio University)***					S-04
10:10-10:50	**Hall I** **Chairperson Eiji Higurashi (Tohoku University) & Mitsuaki Katagiri(Rapidus Corporation)** **Special Speech III**					
10:10	**Special Speech III: Challenges for hetero integration: process technology, test and reliability** ***Rer. nat. Harald Kuhn (Fraunhofer ENAS)***					S-03
10:50	*Coffee break + Sponsor's Exhibition*					
11:00-12:55	**Session 13: Process and Material Technologies II** **Chairperson** **Satomi Kawamoto (Namics Corporation)** **Shinya Takyu (LINTEC Corporation)**		**Session 14: High-Speed Electrical Interconnect** **Chairperson** **Kazuyuki Nakagawa (Renesas Electronics Corporation)** **Yoichiro Kurita (Tokyo Institute of Technology)**		**Session 15: Polymer Waveguide Technology** **Chairperson** **Hideyuki Nawata (Nissan Chemical Corporation)** **Junichi Inoue (Kyoto Institute of Technology)**	
11:00	**(Invited)** TBD *Gari Arutinov* *Holst Centre*	I-04	**(Invited)** A Novel Chiplet Integration Architecture Employing Pillar-Suspended Bridge with Polymer Fine-Via Interconnect *Yasuhiro Morikawa* *ULVAC*	I-11	Demonstration of high-power stability of polymer optical waveguides using external laser source (ELS) for co-packaged optics *Satoshi Suda, Takayuki Kurosu, Akihiro Noriki, Fumi Nakamura, Takeru Amano* *National Institute of Advanced Industrial Science and Technology*	6
11:25	Inductive sintering module for improved multi die attach in the field of power packaging *Christian Hofmann, Patrick Rochala, Martin Kroll, Sushant Panhale, Mario Baum, Maik Wiemer, Harald Kuhn, Kiyoshi Oi* *Fraunhofer Institute for Electronic Nano Systems ENAS, Chemnitz University of Technology, Institute for Machine Tools and Production Processes (IWP), Professorship for Forming and Joining, SHINKO Electric Industries Co., Ltd.*	41	Simulation method of 32Gbps Signal Transmission Considering Xtalk Impact using Probability Density Function *Masahiro Yao, Norio Chujo* *Hitachi, Ltd.*	35	Low Loss Design and Fabrication for Tapered Waveguide Based Spot Size Converter *Fumimasa Kondo, Yuji Furuta, HIsashi Kaneda, Tomoharu Fujii, Takaaki Ishigure* *1) Keio University 2) SHINKO ELECTRIC INDUSTRIES CO., LTD.*	45
11:50	Printable Sheet Sensor System with Organic Circuit for Structural Health Monitoring *Mihoko AKIYAMA, Teppei ARAKI, Takafumi UEMURA, Shusuke YOSHIMOTO, Naoko NAMBA, Yuko KASAI, Hiroshi OHTA, Toshikazu NEZU* *1) Osaka University 2) SANKEN*	21	A 3.6–4.5 GHz Doherty RF Power Amplifier Using 0.25-um GaN/SiC HEMT and GaAs IPD technology *Hsin-Chieh Lin, Hsin-Chieh Lin, Te-Hua Fan, Hwann-Kaeo Chiou, Da-Chiang Chang* *1) National Central University* *2) Taiwan Semiconductor Research Institute*	18	Temperature dependence of coupling loss between SMF and polymer optical waveguides with various refractive index profiles *Ryota Kinoshita, Takaaki Ishigure* *1) Sumitomo Bakelite Co., Ltd. 2) Keio University*	22
12:15	Warpage Observation of Liquid Compression Mold Underfill on Strip Substrate *Takayuki Oe, Yuto Shigeno, Yukihiro Ikeda, Kyota Aoyama, Tsuyoshi Kamimura* *NAMICS CORPORATION*	42	Crosstalk Mitigation for High Speed SerDes Applications on FCBGA Package *Li-Chieh Hung, Hung-Chun Kuo, Ming-Fong Jhong, Chen-Chao Wang* *ASE Inc.*	25	Tactile Pressure Sensor Based on Flexible Polymer Optical Waveguides Fabricated by the Mosquito Method *YUANTIAN YIN, Takaaki Ishigure* *Keio University*	17
12:40	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*		*Interview with the Authors (Discussion after the session)*		*Interview with the Authors (Discussion after the session)*	
12:55	*Lunch (free time)*					
14:25-16:45	**Session 16: Power Electronics** **Chairperson** **Kentaro Kaneko (Ritsumeikan University)** **Hiroki Imabayashi (Fukui University)**		**Session 17: Integrated Photonics** **Chairperson** **Takahiro Matsubara (KYOCERA Corporation)** **Hidetoshi Numata (IBM Research)**		**Session 18: Process and Material Technologies III** **Chairperson** **Naoko Araki(DAICEL CORPORATION)** **Mitsuaki Katagiri(Rapidus Corporation)**	
14:25	**(Invited)** 350℃ operation of SiC complementary JFET logic gates *Mitsuaki Kaneko* *Kyoto University*	I-03	**(Invited)** Energy-Efficient Integrated Photonics for Future Optical Interconnects and Neuromorphic Computing *Stanley Cheung* *Hewlett Packard Labs*	I-08	Development of Anti-ESD back grinding tape *Shinya Takaoka, Issei Adachi* *Lintec Corporation*	10
14:50	The effect of the power module structure (cupper clip thickness) on reliability under power cycling test *Ryoichi Kato, Yoshinari Ikeda, Takafumi Yamada, Kohei Yamauchi, Hiromichi Gohara, Tatsuhiko Asai, Hirohisa Oyama* *Fuji electric Co., Ltd.*	23	Retroreflection Using Bloch Surface Wave Resonance for External Laser Mirror *Keisuke Ozawa, Aika Taniguchi, Yuya Yamanishi, Junichi Inoue, Shogo Ura* *Kyoto Institute of Technology*	53	Development of high heat-resistant multilayer barrier electrodes suitable for multiple reflow processes *KAZUTAKA MAEDA, DAISUKE TOYOTA, SUGURU MISAWA* *KYOCERA Corporation*	18
15:15	Study of Nitride Crack Reduction for Electronic Power Devices *Nick Chenchao Zhong, Haibo Fan, Nivasan Yogeswaran, Mark Gajda* *1) Nexperia Hong Kong 2) Nexperia UK*	3	Polymer Optical Waveguide Type 3-D MUX device for Mode Division Multiplexing Links *Ryoto Ichinose, Takaaki Ishigure* *Keio University*	46	RAC Process characterization in SMT PCBA *Jui Ang Tan, Chee Chuan Tan, Alvin Kok Wah Leong, Viiren Subramaniam, Khian Chee Chua* *Intel Sdn Bhd*	27
15:40	Schottky barrier diode composed of Ge-doped α-Ga2O3 grown by mist-CVD method *Takeru Wakamatsu, Yuki Isobe, Hitoshi Takane, Kentaro Kaneko, Katsuhisa Tanaka* *1) Kyoto University 2) Ritsumeikan University*	55	**(Invited)** Photonic System-in-Package (pSiP) by applying thin glass *Henning Shroder* *Fraunhofer IZM*	I-10	*Interview with the Authors (Discussion after the session)*	
16:05	Prototyping and Evaluation of SiC Half Bridge Circuit using Power Device Embedded Module Process Towards Future Three Dimensional Packaging. *Kazuhito NAKAMURA, Koichi SHIGEMATSU, Jun IMAOKA, Masayoshi YAMAMOTO* *Nagoya University*	38	*Interview with the Authors (Discussion after the session)*			
16:30	*Interview with the Authors (Discussion after the session) + Sponsor's Exhibition*					
16:45	*Close*					